

Mechanical Support System for a Thin Package

Abstract of the Disclosure

5 An electronic package includes an IC, such as a die, mounted onto one side
of a thin interposer and a pin carrier mounted to an opposing side of the interposer.
The pin carrier includes a cavity underneath the die. The cavity allows capacitors,
or other electronic components, to be mounted against the interposer beneath the
die. The cavity in the pin carrier is filled with an encapsulant to mechanically
10 support the thin interposer in the area of the cavity during operation of an electronic
system that includes the package.

"Express Mail" mailing label number: EL873859463US

Date of Deposit: October 24, 2001

This paper or fee is being deposited on the date indicated above with
the United States Postal Service pursuant to 37 CFR 1.10, and is
addressed to the Commissioner for Patents, Box Patent Application,
Washington, D.C. 20231.